



PRELIMINARY

CY7C1512

64K x 8 Static RAM

Features

- **High speed**
 - $t_{AA} = 15 \text{ ns}$
- **CMOS for optimum speed/power**
- **Low active power**
 - 770 mW
- **Low standby power**
 - 28 mW
- **Automatic power-down when deselected**
- **TTL-compatible inputs and outputs**
- **Easy memory expansion with \overline{CE}_1 , CE_2 , and \overline{OE} options**

Functional Description

The CY7C1512 is a high-performance CMOS static RAM organized as 65,536 words by 8 bits. Easy memory expansion is provided by an active LOW chip enable (\overline{CE}_1), an active HIGH chip enable (CE_2), an active LOW output enable (\overline{OE}),

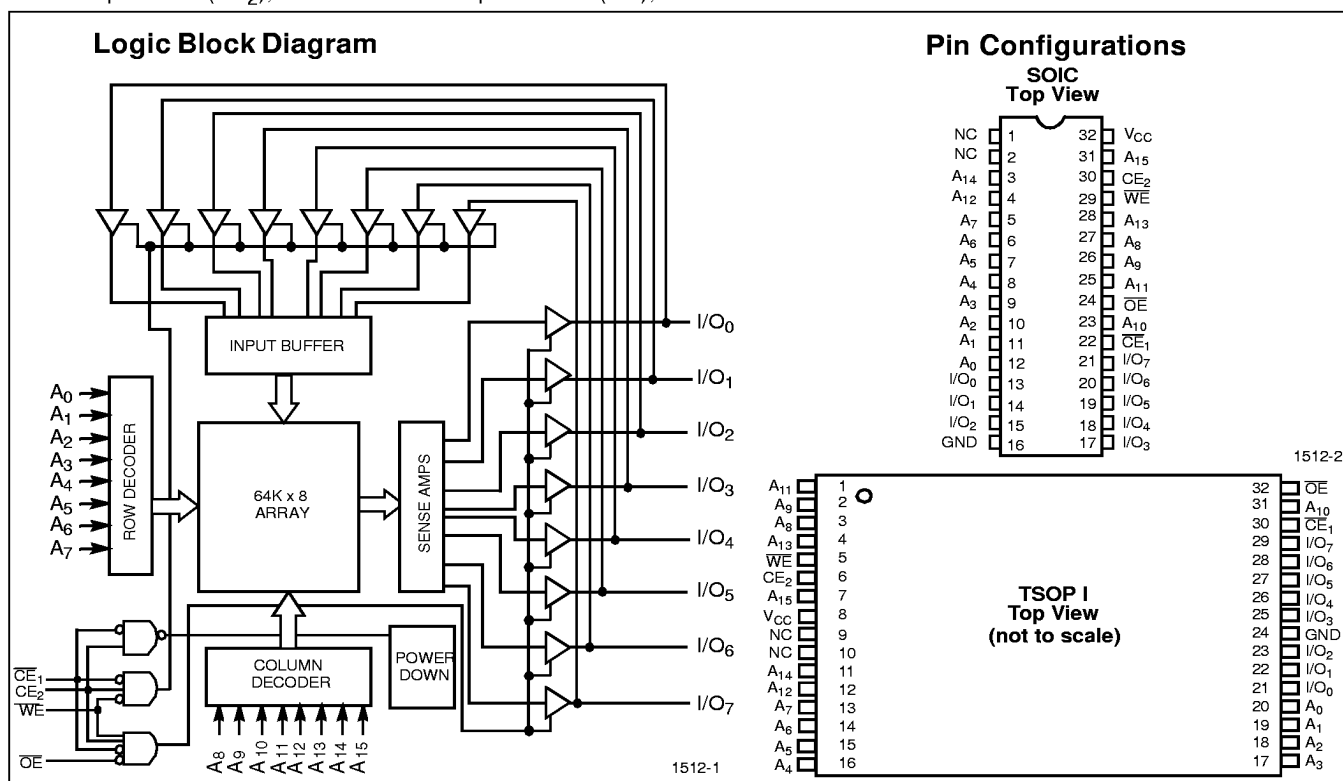
and three-state drivers. This device has an automatic power-down feature that reduces power consumption by more than 75% when deselected.

Writing to the device is accomplished by taking chip enable one (\overline{CE}_1) and write enable (WE) inputs LOW and chip enable two (CE_2) input HIGH. Data on the eight I/O pins (I/O_0 through I/O_7) is then written into the location specified on the address pins (A_0 through A_{15}).

Reading from the device is accomplished by taking chip enable one (\overline{CE}_1) and output enable (\overline{OE}) LOW while forcing write enable (WE) and chip enable two (CE_2) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the I/O pins.

The eight input/output pins (I/O_0 through I/O_7) are placed in a high-impedance state when the device is deselected (\overline{CE}_1 HIGH or CE_2 LOW), the outputs are disabled (\overline{OE} HIGH), or during a write operation (\overline{CE}_1 LOW, CE_2 HIGH, and WE LOW).

The CY7C1512 is available in standard TSOP type I and 450-mil-wide plastic SOIC packages.



Selection Guide

		7C1512-15	7C1512-20	7C1512-25	7C1512-35	7C1512-70
Maximum Access Time (ns)		15	20	25	35	70
Maximum Operating Current (mA)	Commercial	140	130	120	110	110
Maximum CMOS Standby Current (mA)	Commercial	5	5	5	5	5

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with Power Applied -55°C to +125°C

Supply Voltage on V_{CC} to Relative GND^[1] -0.5V to +7.0V

DC Voltage Applied to Outputs in High Z State^[1] -0.5V to $V_{CC} + 0.5V$

DC Input Voltage^[1] -0.5V to $V_{CC} + 0.5V$

Current into Outputs (LOW) 20 mA

Static Discharge Voltage >2001V
(per MIL-STD-883, Method 3015)

Latch-Up Current >200 mA

Operating Range

Range	Ambient Temperature ^[2]	V_{CC}
Commercial	0°C to +70°C	5V ± 10%
Industrial	-40°C to +85°C	5V ± 10%

Electrical Characteristics Over the Operating Range^[3]

Parameter	Description	Test Conditions	7C1512-15		7C1512-20		7C1512-25		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		2.4		2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$		0.4		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	V
V_{IL}	Input LOW Voltage ^[1]		-0.3	0.8	-0.3	0.8	-0.3	0.8	V
I_{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$	-1	+1	-1	+1	-1	+1	μA
I_{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC}$, Output Disabled	-5	+5	-5	+5	-5	+5	μA
I_{OS}	Output Short Circuit Current ^[4]	$V_{CC} = \text{Max.}, V_{OUT} = GND$		-300		-300		-300	mA
I_{CC}	V_{CC} Operating Supply Current	$V_{CC} = \text{Max.}, I_{OUT} = 0 \text{ mA}, f = f_{MAX} = 1/t_{RC}$		140		130		120	mA
I_{SB1}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC} , $\overline{CE}_1 \geq V_{IH}$ or $CE_2 \leq V_{IL}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, $f = f_{MAX}$		40		30		30	mA
I_{SB2}	Automatic CE Power-Down Current — CMOS Inputs	Max. V_{CC} , $\overline{CE}_1 \geq V_{CC} - 0.3V$, or $CE_2 \leq 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$, or $V_{IN} \leq 0.3V$, $f=0$		5		5		5	mA

Parameter	Description	Test Conditions	7C1512-35		7C1512-70		Unit
			Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	V
V_{IL}	Input LOW Voltage ^[1]		-0.3	0.8	-0.3	0.8	V
I_{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$	-1	+1	-1	+1	μA
I_{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC}$, Output Disabled	-5	+5	-5	+5	μA
I_{OS}	Output Short Circuit Current ^[4]	$V_{CC} = \text{Max.}, V_{OUT} = GND$		-300		-300	mA
I_{CC}	V_{CC} Operating Supply Current	$V_{CC} = \text{Max.}, I_{OUT} = 0 \text{ mA}, f = f_{MAX} = 1/t_{RC}$		110		110	mA
I_{SB1}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC} , $\overline{CE}_1 \geq V_{IH}$ or $CE_2 \leq V_{IL}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, $f = f_{MAX}$		25		25	mA
I_{SB2}	Automatic CE Power-Down Current — CMOS Inputs	Max. V_{CC} , $\overline{CE}_1 \geq V_{CC} - 0.3V$, or $CE_2 \leq 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$, or $V_{IN} \leq 0.3V$, $f=0$		5		5	mA

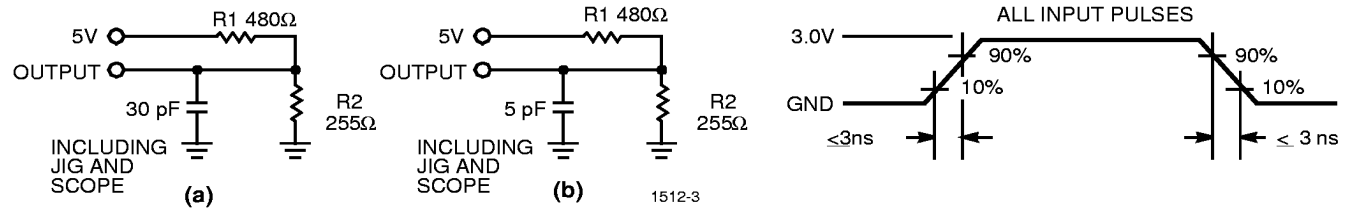
Notes:

- $V_{IL}(\text{min.}) = -2.0V$ for pulse durations of less than 20 ns.
- T_A is the "instant on" case temperature.
- See the last page of this specification for Group A subgroup testing information.
- Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.

Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	$T_A = 25^\circ\text{C}$, $f = 1\text{ MHz}$, $V_{CC} = 5.0\text{V}$	9	pF
C_{OUT}	Output Capacitance		9	pF

AC Test Loads and Waveforms



Equivalent to: THVENIN EQUIVALENT
OUTPUT \rightarrow 167Ω \rightarrow 1.73V

Switching Characteristics^[3, 6] Over the Operating Range

Parameter	Description	7C1512-15		7C1512-20		7C1512-25		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE								
t _{RC}	Read Cycle Time	15		20		25		ns
t _{AA}	Address to Data Valid		15		20		25	ns
t _{OHA}	Data Hold from Address Change	3		3		5		ns
t _{ACE}	\overline{CE}_1 LOW to Data Valid, CE ₂ HIGH to Data Valid		15		20		25	ns
t _{DOE}	\overline{OE} LOW to Data Valid		7		8		10	ns
t _{LZOE}	\overline{OE} LOW to Low Z	0		0		0		ns
t _{HZOE}	\overline{OE} HIGH to High Z ^[7, 8]		7		8		10	ns
t _{LZCE}	\overline{CE}_1 LOW to Low Z, CE ₂ HIGH to Low Z ^[8]	3		3		5		ns
t _{HZCE}	\overline{CE}_1 HIGH to High Z, CE ₂ LOW to High Z ^[7, 8]		7		8		10	ns
t _{PU}	\overline{CE}_1 LOW to Power-Up, CE ₂ HIGH to Power-Up	0		0		0		ns
t _{PD}	\overline{CE}_1 HIGH to Power-Down, CE ₂ LOW to Power-Down		15		20		25	ns
WRITE CYCLE ^[9]								
t _{WC}	Write Cycle Time	15		20		25		ns
t _{SCE}	\overline{CE}_1 LOW to Write End, CE ₂ HIGH to Write End	12		15		20		ns
t _{AW}	Address Set-Up to Write End	12		15		20		ns
t _{HA}	Address Hold from Write End	0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		ns
t _{PWE}	\overline{WE} Pulse Width	12		15		20		ns
t _{SD}	Data Set-Up to Write End	8		10		15		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{LZWE}	\overline{WE} HIGH to Low Z ^[8]	3		3		5		ns
t _{HZWE}	\overline{WE} LOW to High Z ^[7, 8]		7		8		10	ns

5. Tested initially and after any design or process changes that may affect these parameters.

6. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.

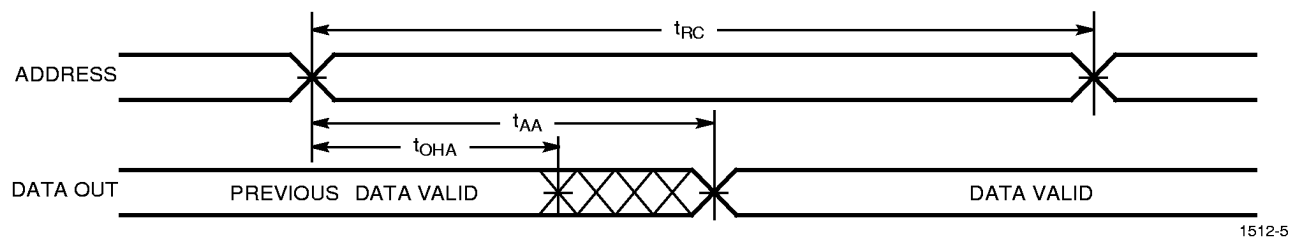
7. t_{LZOE} , t_{HZCE} , and t_{LZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured $\pm 500\text{ mV}$ from steady-state voltage.

8. At any given temperature and voltage condition, t_{HZOE} is less than t_{LZOE} , t_{HZCE} is less than t_{LZCE} , and t_{HZWE} is less than t_{LZWE} for any given device.

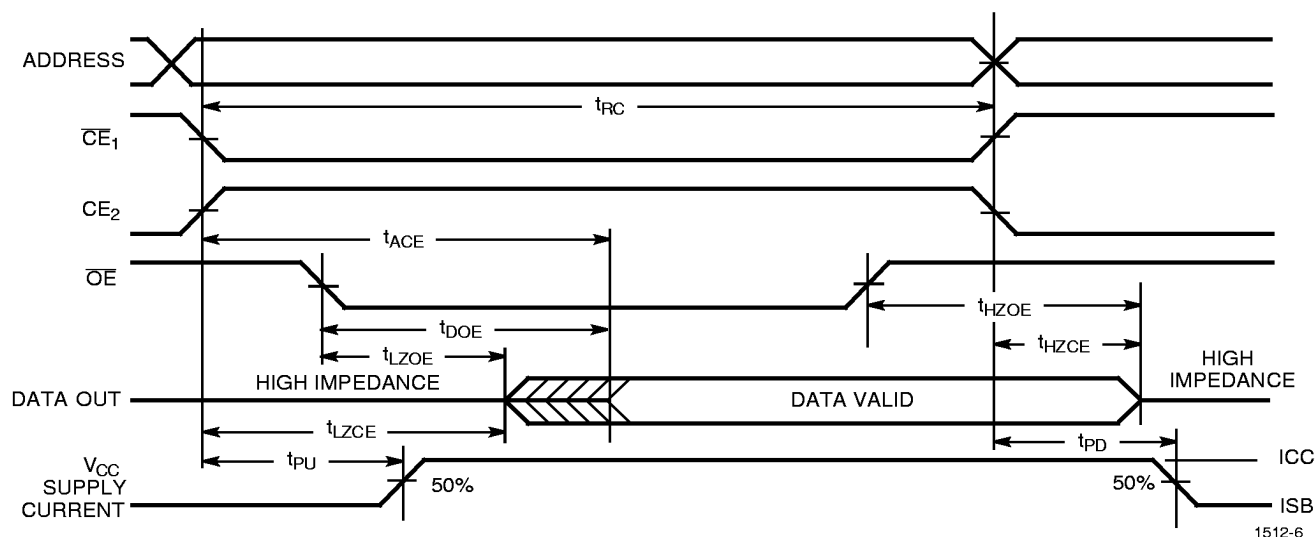
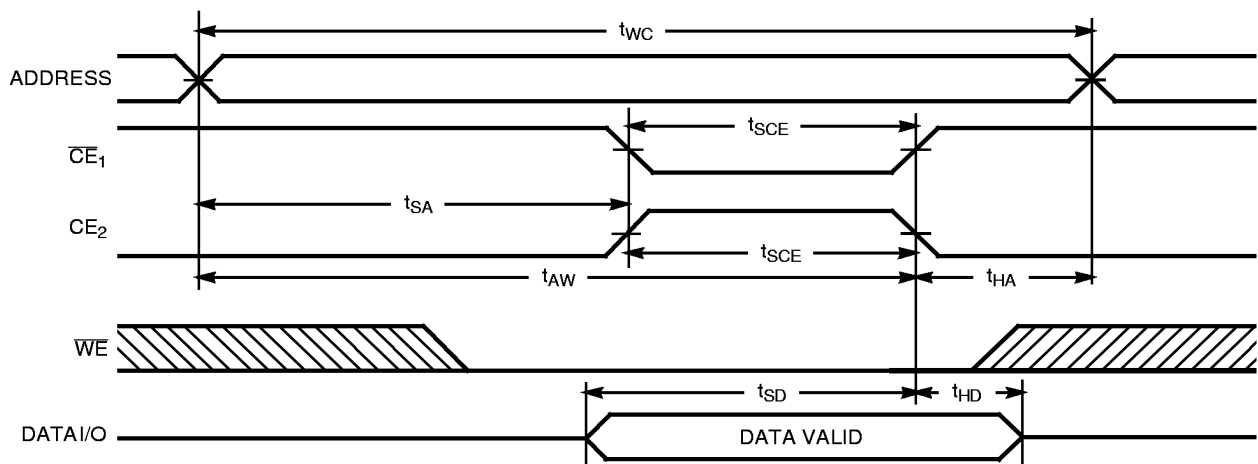
9. The internal write time of the memory is defined by the overlap of \overline{CE}_1 LOW, CE_2 HIGH, and \overline{WE} LOW. \overline{CE}_1 and \overline{WE} must be LOW and CE_2 HIGH to initiate a write, and the transition of any of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.

Switching Characteristics^[3, 6] Over the Operating Range (continued)

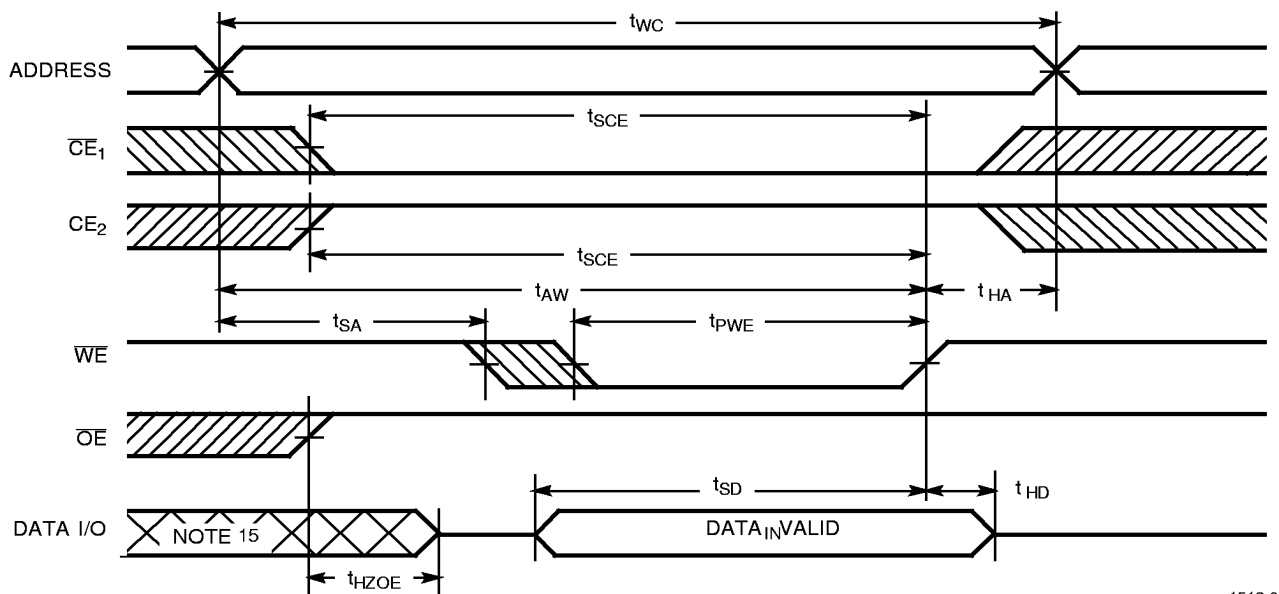
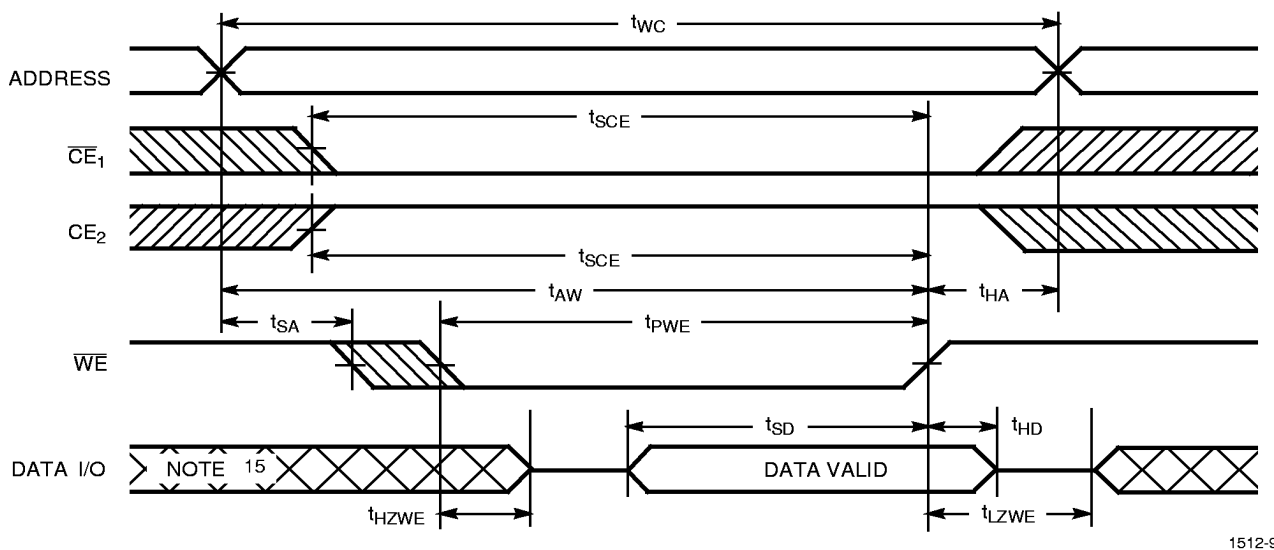
Parameter	Description	7C1512-35		7C1512-70		Unit
		Min.	Min.	Min.	Min.	
READ CYCLE						
t _{RC}	Read Cycle Time	35		70		ns
t _{AA}	Address to Data Valid		35		70	ns
t _{OHA}	Data Hold from Address Change	5		5		ns
t _{ACE}	\overline{CE}_1 LOW to Data Valid, CE_2 HIGH to Data Valid		35		70	ns
t _{DOE}	\overline{OE} LOW to Data Valid		15		15	ns
t _{LZOE}	\overline{OE} LOW to Low Z	0		0		ns
t _{HZOE}	\overline{OE} HIGH to High Z ^[7, 8]		15		15	ns
t _{LZCE}	\overline{CE}_1 LOW to Low Z, CE_2 HIGH to Low Z ^[8]	5		5		ns
t _{HZCE}	\overline{CE}_1 HIGH to High Z, CE_2 LOW to High Z ^[7, 8]		15		15	ns
t _{PU}	\overline{CE}_1 LOW to Power-Up, CE_2 HIGH to Power-Up	0		0		ns
t _{PD}	\overline{CE}_1 HIGH to Power-Down, CE_2 LOW to Power-Down		35		70	ns
WRITE CYCLE ^[9]						
t _{WC}	Write Cycle Time	35		70		ns
t _{SCE}	\overline{CE}_1 LOW to Write End, CE_2 HIGH to Write End	25		60		ns
t _{AW}	Address Set-Up to Write End	25		60		ns
t _{HA}	Address Hold from Write End	0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		ns
t _{PWE}	\overline{WE} Pulse Width	25		60		ns
t _{SD}	Data Set-Up to Write End	20		55		ns
t _{HD}	Data Hold from Write End	0		0		ns
t _{LZWE}	\overline{WE} HIGH to Low Z ^[8]	5		5		ns
t _{HZWE}	\overline{WE} LOW to High Z ^[7, 8]		15		15	ns

Switching Waveforms
Read Cycle No. 1 ^[10, 11]

Notes:

10. Device is continuously selected. \overline{OE} , $\overline{CE}_1 = V_{IL}$, $CE_2 = V_{IH}$.
 11. \overline{WE} is HIGH for read cycle.

Switching Waveforms (continued)
Read Cycle No. 2 (\overline{OE} Controlled) [11, 12]

Write Cycle No. 1 (\overline{CE}_1 or CE_2 Controlled) [13, 14]

Notes:

12. Address valid prior to or coincident with \overline{CE}_1 transition LOW and CE_2 transition HIGH.
13. Data I/O is high impedance if $\overline{OE} = V_{IH}$.
14. If \overline{CE}_1 goes HIGH or CE_2 goes LOW simultaneously with \overline{WE} going HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)
Read Cycle No. 2 (WE Controlled, \overline{OE} HIGH During Write)^[13, 14]

Write Cycle No. 3 (WE Controlled, \overline{OE} LOW)^[14]

Note:

15. During this period the I/Os are in the output state and input signals should not be applied.



Truth Table

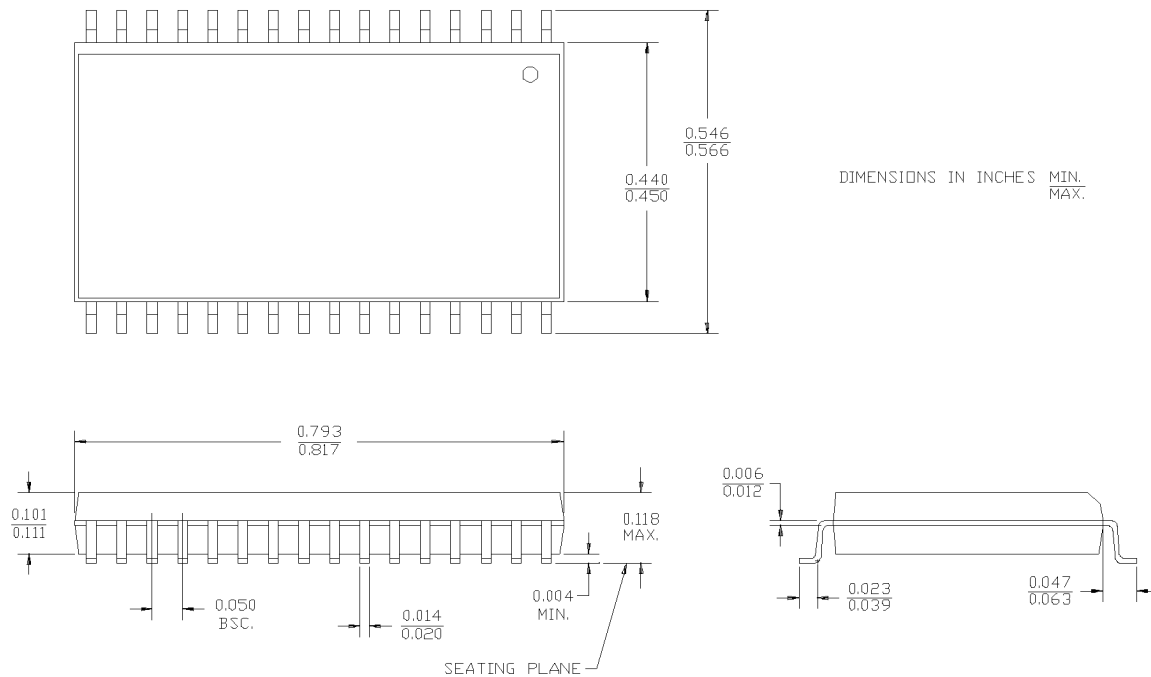
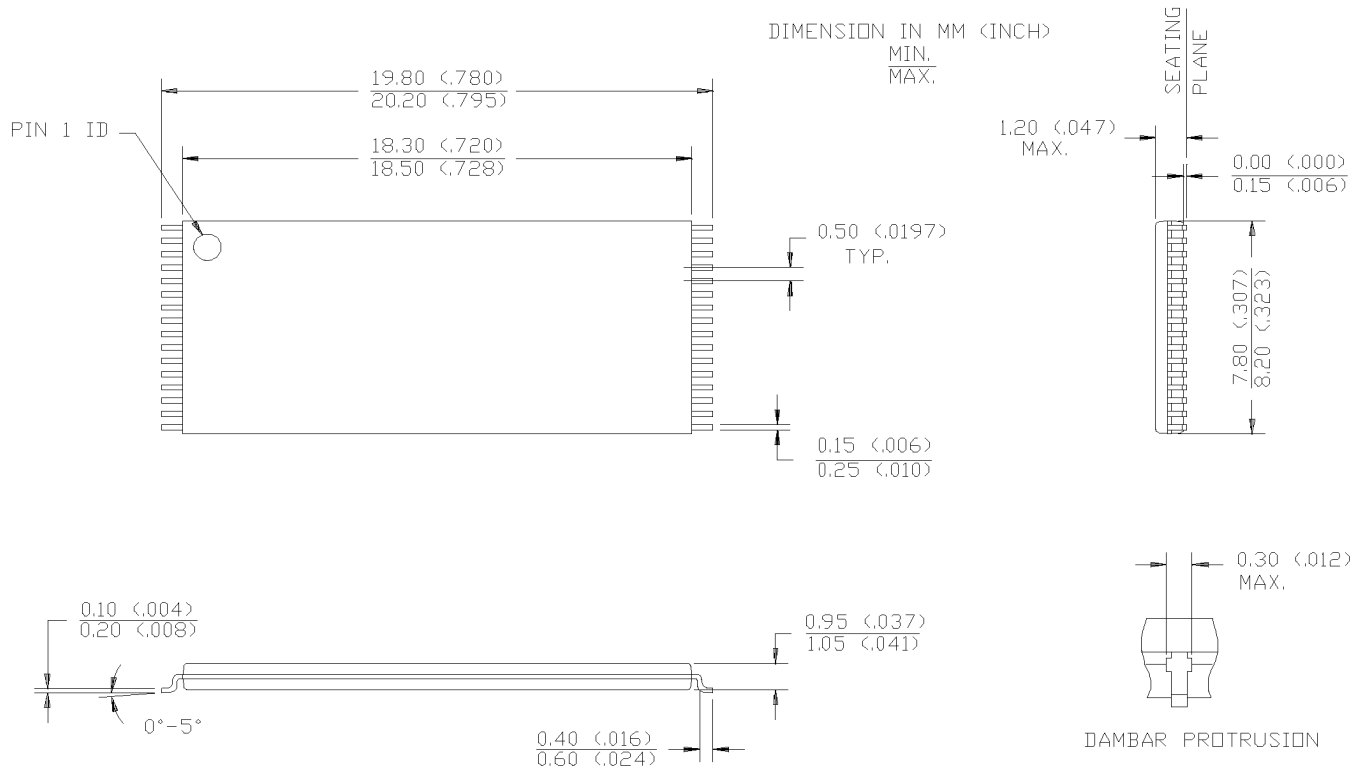
CE ₁	CE ₂	OE	WE	I/O ₀ – I/O ₇	Mode	Power
H	X	X	X	High Z	Power-Down	Standby (I _{SB})
X	L	X	X	High Z	Power-Down	Standby (I _{SB})
L	H	L	H	Data Out	Read	Active (I _{CC})
L	H	X	L	Data In	Write	Active (I _{CC})
L	H	H	H	High Z	Selected, Outputs Disabled	Active (I _{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
15	CY7C1512-15SC	S34	32-Lead (450-Mil) Molded SOIC	Commercial
	CY7C1512-15ZC	Z32	32-Lead TSOP Type I	
	CY7C1512-20ZI	Z32	32-Lead TSOP Type I	Industrial
20	CY7C1512-20SC	S34	32-Lead (450-Mil) Molded SOIC	Commercial
	CY7C1512-20ZC	Z32	32-Lead TSOP Type I	
	CY7C1512-20ZI	Z32	32-Lead TSOP Type I	Industrial
25	CY7C1512-25SC	S34	32-Lead (450-Mil) Molded SOIC	Commercial
	CY7C1512-25ZC	Z32	32-Lead TSOP Type I	
	CY7C1512-25ZI	Z32	32-Lead TSOP Type I	Industrial
35	CY7C1512-35SC	S34	32-Lead (450-Mil) Molded SOIC	Commercial
70	CY7C1512-70SC	S34	32-Lead (450-Mil) Molded SOIC	Commercial
	CY7C1512-70ZC	Z32	32-Lead TSOP Type I	
	CY7C1512-70ZI	Z32	32-Lead TSOP Type I	Industrial

Shaded areas contain advanced information.

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Package Diagrams
32-Lead (450 -Mil) Molded SOIC S34

32-Lead Thin Small Outline Package Z32


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